B6 Summary (Official Form 6 - Summary) (12/14)

United States Bankruptcy Court
Northern District of California

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

Chapter **11**

SUMMARY OF SCHEDULES

Indicate as to each schedule whether that schedule is attached and state the number of pages in each. Report the totals from Schedules A, B, D, E, F, I, and J in the boxes provided. Add the amounts from Schedules A and B to determine the total amount of the debtor's assets. Add the amounts of all claims from Schedules D, E, and F to determine the total amount of the debtor's liabilities. Individual debtors must also complete the "Statistical Summary of Certain Liabilities and Related Data" if they file a case under chapter 7, 11, or 13.

NAME OF SCHEDULE	ATTACHED (YES/NO)	NO. OF SHEETS	ASSETS	LIABILITIES	OTHER
A - Real Property	**Yes**	**1**	**0.00**		
B - Personal Property	**Yes**	**10**	**16,559,802.83**		
C - Property Claimed as Exempt	**No**	**0**			
D - Creditors Holding Secured Claims	**Yes**	**1**		**7,688,182.09**	
E - Creditors Holding Unsecured Priority Claims (Total of Claims on Schedule E)	**Yes**	**2**		**186.00**	
F - Creditors Holding Unsecured Nonpriority Claims	**Yes**	**6**		**262,675.10**	
G - Executory Contracts and Unexpired Leases	**Yes**	**1**			
H - Codebtors	**Yes**	**1**			
I - Current Income of Individual Debtor(s)	**No**	**0**			**N/A**
J - Current Expenditures of Individual Debtor(s)	**No**	**0**			**N/A**
Total Number of Sheets of ALL Schedules		**22**			
		Total Assets	**16,559,802.83**		
			Total Liabilities	**7,951,043.19**	

United States Bankruptcy Court
Northern District of California

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

Chapter **11**

STATISTICAL SUMMARY OF CERTAIN LIABILITIES AND RELATED DATA (28 U.S.C. § 159)

If you are an individual debtor whose debts are primarily consumer debts, as defined in § 101(8) of the Bankruptcy Code (11 U.S.C.§ 101(8)), filing a case under chapter 7, 11 or 13, you must report all information requested below.

☐ Check this box if you are an individual debtor whose debts are NOT primarily consumer debts. You are not required to report any information here.

This information is for statistical purposes only under 28 U.S.C. § 159.

Summarize the following types of liabilities, as reported in the Schedules, and total them.

Type of Liability	**Amount**
Domestic Support Obligations (from Schedule E)	
Taxes and Certain Other Debts Owed to Governmental Units (from Schedule E)	
Claims for Death or Personal Injury While Debtor Was Intoxicated (from Schedule E) (whether disputed or undisputed)	
Student Loan Obligations (from Schedule F)	
Domestic Support, Separation Agreement, and Divorce Decree Obligations Not Reported on Schedule E	
Obligations to Pension or Profit-Sharing, and Other Similar Obligations (from Schedule F)	
TOTAL	

State the following:

Average Income (from Schedule I, Line 12)	
Average Expenses (from Schedule J, Line 22)	
Current Monthly Income (from Form 22A-1 Line 11; OR, Form 22B Line 14; OR, Form 22C-1 Line 14)	

State the following:

1. Total from Schedule D, "UNSECURED PORTION, IF ANY" column		
2. Total from Schedule E, "AMOUNT ENTITLED TO PRIORITY" column		
3. Total from Schedule E, "AMOUNT NOT ENTITLED TO PRIORITY, IF ANY" column		
4. Total from Schedule F		
5. Total of non-priority unsecured debt (sum of 1, 3, and 4)		

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

SCHEDULE A - REAL PROPERTY

Except as directed below, list all real property in which the debtor has any legal, equitable, or future interest, including all property owned as a cotenant, community property, or in which the debtor has a life estate. Include any property in which the debtor holds rights and powers exercisable for the debtor's own benefit. If the debtor is married, state whether husband, wife, both, or the marital community own the property by placing an "H," "W," "J," or "C" in the column labeled "Husband, Wife, Joint, or Community." If the debtor holds no interest in real property, write "None" under "Description and Location of Property."

Do not include interests in executory contracts and unexpired leases on this schedule. List them in Schedule G - Executory Contracts and Unexpired Leases.

If an entity claims to have a lien or hold a secured interest in any property, state the amount of the secured claim. See Schedule D. If no entity claims to hold a secured interest in the property, write "None" in the column labeled "Amount of Secured Claim." If the debtor is an individual or if a joint petition is filed, state the amount of any exemption claimed in the property only in Schedule C - Property Claimed as Exempt.

Description and Location of Property	Nature of Debtor's Interest in Property	Husband, Wife, Joint, or Community	Current Value of Debtor's Interest in Property, without Deducting any Secured Claim or Exemption	Amount of Secured Claim
None				

Sub-Total >	**0.00**	(Total of this page)
Total >	**0.00**	

0 continuation sheets attached to the Schedule of Real Property

(Report also on Summary of Schedules)

In re **Silicon Genesis Corporation**, Case No. **15-50525 MEH**
Debtor

SCHEDULE B - PERSONAL PROPERTY

Except as directed below, list all personal property of the debtor of whatever kind. If the debtor has no property in one or more of the categories, place an "x" in the appropriate position in the column labeled "None." If additional space is needed in any category, attach a separate sheet properly identified with the case name, case number, and the number of the category. If the debtor is married, state whether husband, wife, both, or the marital community own the property by placing an "H," "W," "J," or "C" in the column labeled "Husband, Wife, Joint, or Community." If the debtor is an individual or a joint petition is filed, state the amount of any exemptions claimed only in Schedule C - Property Claimed as Exempt.

Do not list interests in executory contracts and unexpired leases on this schedule. List them in Schedule G - Executory Contracts and Unexpired Leases.

If the property is being held for the debtor by someone else, state that person's name and address under "Description and Location of Property." If the property is being held for a minor child, simply state the child's initials and the name and address of the child's parent or guardian, such as "A.B., a minor child, by John Doe, guardian." Do not disclose the child's name. See, 11 U.S.C. §112 and Fed. R. Bankr. P. 1007(m).

Type of Property	NONE	Description and Location of Property	Husband, Wife, Joint, or Community	Current Value of Debtor's Interest in Property, without Deducting any Secured Claim or Exemption
1. Cash on hand	X			
2. Checking, savings or other financial accounts, certificates of deposit, or shares in banks, savings and loan, thrift, building and loan, and homestead associations, or credit unions, brokerage houses, or cooperatives.		**Operating Account, Silicon Valley Bank**	-	**147,930.00**
		Payroll Account, Silicon Valley Bank	-	**0.00**
		Sweep Account, Silicon Valley Bank	-	**0.00**
3. Security deposits with public utilities, telephone companies, landlords, and others.	X			
4. Household goods and furnishings, including audio, video, and computer equipment.	X			
5. Books, pictures and other art objects, antiques, stamp, coin, record, tape, compact disc, and other collections or collectibles.	X			
6. Wearing apparel.	X			
7. Furs and jewelry.	X			
8. Firearms and sports, photographic, and other hobby equipment.	X			
9. Interests in insurance policies. Name insurance company of each policy and itemize surrender or refund value of each.	X			
10. Annuities. Itemize and name each issuer.	X			

Sub-Total > **147,930.00**
(Total of this page)

5 continuation sheets attached to the Schedule of Personal Property

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

SCHEDULE B - PERSONAL PROPERTY

(Continuation Sheet)

Type of Property	N O N E	Description and Location of Property	Husband, Wife, Joint, or Community	Current Value of Debtor's Interest in Property, without Deducting any Secured Claim or Exemption
11. Interests in an education IRA as defined in 26 U.S.C. § 530(b)(1) or under a qualified State tuition plan as defined in 26 U.S.C. § 529(b)(1). Give particulars. (File separately the record(s) of any such interest(s). 11 U.S.C. § 521(c).)	X			
12. Interests in IRA, ERISA, Keogh, or other pension or profit sharing plans. Give particulars.	X			
13. Stock and interests in incorporated and unincorporated businesses. Itemize.	X			
14. Interests in partnerships or joint ventures. Itemize.	X			
15. Government and corporate bonds and other negotiable and nonnegotiable instruments.	X			
16. Accounts receivable.		**liquidated payments due under license agreements**	-	**1,516,060.50**
17. Alimony, maintenance, support, and property settlements to which the debtor is or may be entitled. Give particulars.	X			
18. Other liquidated debts owed to debtor including tax refunds. Give particulars.		**Judgment against Legalforce, Inc., and Raj Abhyanker, P.C.**	-	**462,812.33**
19. Equitable or future interests, life estates, and rights or powers exercisable for the benefit of the debtor other than those listed in Schedule A - Real Property.	X			
20. Contingent and noncontingent interests in estate of a decedent, death benefit plan, life insurance policy, or trust.	X			
21. Other contingent and unliquidated claims of every nature, including tax refunds, counterclaims of the debtor, and rights to setoff claims. Give estimated value of each.		**patent infringement claims**	-	**Unknown**

Sub-Total > **1,978,872.83**
(Total of this page)

Sheet **1** of **5** continuation sheets attached to the Schedule of Personal Property

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

SCHEDULE B - PERSONAL PROPERTY

(Continuation Sheet)

Type of Property	NONE	Description and Location of Property	Husband, Wife, Joint, or Community	Current Value of Debtor's Interest in Property, without Deducting any Secured Claim or Exemption
22. Patents, copyrights, and other intellectual property. Give particulars.		**See Attachment B.22**	**-**	**Unknown**
23. Licenses, franchises, and other general intangibles. Give particulars.		**NPV of projected royalties due under license agreement with Shin-Etsu Chemical Co., Ltd.**	**-**	**7,500,000.00**
		NPV of projected royalties due under license agreement with EV Group E. Thallner GmbH	**-**	**1,000,000.00**
		NPV of projected royalties due under license agreements with Applied Materials and QMAT, Inc.	**-**	**Unknown**
24. Customer lists or other compilations containing personally identifiable information (as defined in 11 U.S.C. § 101(41A)) provided to the debtor by individuals in connection with obtaining a product or service from the debtor primarily for personal, family, or household purposes.	**X**			
25. Automobiles, trucks, trailers, and other vehicles and accessories.	**X**			
26. Boats, motors, and accessories.	**X**			
27. Aircraft and accessories.	**X**			
28. Office equipment, furnishings, and supplies.	**X**			
29. Machinery, fixtures, equipment, and supplies used in business.		**Cryo pump** **Cyclotron Cyro pump parts**	**-**	**5,000.00**
		Edwards QDP-40 **dry pump**	**-**	**1,000.00**
		Korvis Asyst Robot **spare robot for spa tool**	**-**	**10,000.00**
		Power supply **HV stack - for P-III**	**-**	**500.00**
		Manual PA **Manual plasma activation tool**	**-**	**200,000.00**
		Robot isoports **FOUP Openers**	**-**	**50,000.00**

Sub-Total > **8,766,500.00**
(Total of this page)

Sheet **2** of **5** continuation sheets attached to the Schedule of Personal Property

In re **Silicon Genesis Corporation**, Case No. **15-50525 MEH**
Debtor

SCHEDULE B - PERSONAL PROPERTY

(Continuation Sheet)

Type of Property	N O N E	Description and Location of Property	Husband, Wife, Joint, or Community	Current Value of Debtor's Interest in Property, without Deducting any Secured Claim or Exemption
		rT-CCP **room temperature cleave tool**	-	**1,000,000.00**
		rT-CCP **room temperature cleave tool - used**	-	**250,000.00**
		SPA **automated plasma activation tool**	-	**1,000,000.00**
		Allwin Gen3+ **Rapid Thermal Oven**	-	**100,000.00**
		RD-4 accelerator **1.1 MeV implant system**	-	**2,500,000.00**
		Allwin Gen2 **Rapid Thermal Oven**	-	**10,000.00**
		Allwin Gen3 **Rapid Thermal Oven**	-	**75,000.00**
		Ansys FEA Software **finite element analysis**	-	**5,000.00**
		Bede-1 XRD **xray diffraction tool**	-	**10,000.00**
		Blue M#1 **Blue M-Oven**	-	**5,000.00**
		IDE AFM **Atomic Force Microscope**	-	**50,000.00**
		Lab Tables and Benches **tables and benches**	-	**1,000.00**
		Manual PA **R&D tool**	-	**5,000.00**
		Nikon Microscope **microscope**	-	**5,000.00**
		Office Furniture **FH and PO offices**	-	**1,000.00**
		Olympus Microscope **microscope**	-	**5,000.00**

Sub-Total > **5,022,000.00**
(Total of this page)

Sheet **3** of **5** continuation sheets attached
to the Schedule of Personal Property

In re **Silicon Genesis Corporation**, Case No. **15-50525 MEH**

Debtor

SCHEDULE B - PERSONAL PROPERTY

(Continuation Sheet)

Type of Property	N O N E	Description and Location of Property	Husband, Wife, Joint, or Community	Current Value of Debtor's Interest in Property, without Deducting any Secured Claim or Exemption
		P-III Implanter **Plasma implant tool**	**-**	**200,000.00**
		QA Wet Bench **Solven clean sink**	**-**	**15,000.00**
		Rofin-Sinar Diode Laser **Laser**	**-**	**25,000.00**
		TC Bonder **Manual bonding tool**	**-**	**10,000.00**
		Toshiba 4520c Copier **copy machine**	**-**	**10,000.00**
		Universal Wet Bench **Acid clean sink**	**-**	**25,000.00**
		Cyclotron **4.0 MeV Cyclotron Implanter**	**-**	**150,000.00**
		Delage Landon Forklift **forklift**	**-**	**2,500.00**
		Dynamitron End Station **Dynamitron End Station**	**-**	**100,000.00**
		Heidehan **spectrometer**	**-**	**1,000.00**
		Sinton BCT-300 Tester **Solar wafer lifetime tool**	**-**	**20,000.00**
		Summitt air compressor **air compressor system/vac**	**-**	**1,000.00**
		GE DI-H20 - 1500-gal **deionized water system**	**-**	**20,000.00**
		YORK Chiller **water chiller**	**-**	**15,000.00**
		Carrier Chiller **water chiller**	**-**	**5,000.00**
		Kobelco CDA Tower/60hp **clean dry air**	**-**	**25,000.00**

Sub-Total > **624,500.00**
(Total of this page)

Sheet **4** of **5** continuation sheets attached to the Schedule of Personal Property

In re **Silicon Genesis Corporation**, Debtor Case No. **15-50525 MEH**

SCHEDULE B - PERSONAL PROPERTY

(Continuation Sheet)

Type of Property	NONE	Description and Location of Property	Husband, Wife, Joint, or Community	Current Value of Debtor's Interest in Property, without Deducting any Secured Claim or Exemption
		Acid cabinets **hazardous chemical storage**	**-**	**5,000.00**
		Clean Room Components **soft wall clean room/hepa filters**	**-**	**15,000.00**
30. Inventory.	**X**			
31. Animals.	**X**			
32. Crops - growing or harvested. Give particulars.	**X**			
33. Farming equipment and implements.	**X**			
34. Farm supplies, chemicals, and feed.	**X**			
35. Other personal property of any kind not already listed. Itemize.	**X**			

Sub-Total > **20,000.00**
(Total of this page)

Total > **16,559,802.83**

Sheet **5** of **5** continuation sheets attached to the Schedule of Personal Property

(Report also on Summary of Schedules)

ATTACHMENT B.22

SiGen Patent Portfolio

Patent Number	Country	Filed	Issued	Title
US20130209740A1 Feb 13,2012	USA	2/13/2013	n/a	Apparatus and Method of Cleaving Thin Layer from Bulk Material
Sapphire continuation patent (confidential)	USA		n/a	Apparatus and Method of Cleaving Thin Layer from Bulk Material

0842307	EPO	07/2/1996	04/21/2004	System For The Plasma Treatment Of Large Area Substrates
1194949	Germany	04/20/2000	04/11/2000	Surface Finishing of SOI Substrates Using an EPI Process
1194949	France	04/20/2000	12/12/2000	Surface Finishing of SOI Substrates Using an EPI Process
1194949	EPO	04/20/2000	05/06/2003	Surface Finishing of SOI Substrates Using an EPI Process
2409340	UK	10/03/2003	09/18/2001	Method for Treating Semiconductor Material
4128217	Japan	07/2/1996	12/12/2000	Plasma Treatment Apparatus for Large Area Substrates
5653811	USA	07/19/1995	11/14/2000	System for the Plasma Treatment of Large Area Substrates
5945012	USA	02/17/1998	01/04/2000	Tumbling Barrel Plasma Processor
5985742	USA	02/19/1998	01/01/2002	Controlled Cleavage Process and Device for Patterned Films
5994207	USA	02/19/1998	06/12/2001	Controlled Cleavage Process Using Pressurized Fluid
6010579	USA	02/19/1998	12/05/2000	Reusable Substrate for Thin Film Separation
6013563	USA	02/19/1998	11/30/1999	Controlled Cleaving Process
6013567	USA	05/05/1999	01/11/2000	Controlled Cleavage Process Using Pressurized Fluid
6033974	USA	08/10/1999	01/28/2003	Method for Controlled Cleaving Process
6048411	USA	02/19/1998	09/18/2001	Silicon-On-Silicon Hybrid Wafer Assembly
6051073	USA	06/03/1998	03/07/2000	Perforated Shield for Plasma Immersion Ion Implantation
6083324	USA	02/19/1998	09/04/2001	Gettering Technique for Silicon-on-Insulator Wafers
6103599	USA	06/03/1998	11/26/2002	Planarizing Technique for Multilayered Substrates
6113735	USA	03/01/1999	06/24/2003	Novel Distributed System and Code for Control and Automation of Plasma Immersion Ion Implanter
6120660	USA	12/18/1998	09/14/2004	Removable Liner Design for Plasma Immersion Ion Implantation
6146979	USA	02/19/1998	03/25/2008	Pressurized Microbubble Thin Film Separation Process Using a Reusable Substrate
6153524	USA	07/28/1998	12/30/2008	Cluster Tool Method Using Plasma Immersion Ion Implantation
6155909	USA	02/19/1998	11/16/1999	Controlled Cleavage System Using Pressurized Fluid
6159824	USA	02/19/1998	02/13/2001	Silicon-on-Silicon Wafer Bonding Process Using a Thin Film Blister-Separation Method
6159825	USA	02/19/1998	03/04/2003	Controlled Cleavage Thin Film Separation Process Using a Reusable Substrate
6162705	USA	02/19/1998	01/11/2000	Controlled Cleavage Process and Resulting Device Using Beta Annealing
6171965	USA	04/21/1999	09/25/2001	Treatment Method of Cleaved Film for the Manufacture of Substrates
6180496	USA	08/28/1998	10/14/2003	In Situ Plasma Wafer Bonding Method
6184111	USA	08/10/1999	01/09/2007	Pre-Semiconductor Process Implant and Post-Process Film Separation
6186091	USA	10/02/1998	05/13/2008	Shielded Platen Design for Plasma Immersion Ion Implantation
6187110	USA	05/21/1999	07/20/2010	Device for Patterned Films
6204151	USA	04/21/1999	08/12/2008	Smoothing Method for Cleaved Films Made Using Thermal Treatment
6207005	USA	07/28/1998	08/17/2010	Cluster Tool Apparatus Using Plasma Immersion Ion Implantation
6213050	USA	12/01/1998	08/24/2010	Enhanced Plasma Mode and Computer System for Plasma Immersion Ion Implantation
6217724	USA	12/18/1998	12/19/2000	Coated Platen Design for Plasma Immersion Ion Implantation
6221740	USA	08/10/1999	10/01/2002	Substrate Cleaving Tool and Method
6221774	USA	04/05/1999	12/07/2010	Method for Surface Treatment of Substrates
6228176	USA	06/03/1998	09/06/2011	Contoured Platen Design for Plasma Immersion Ion Implantation
6245161	USA	02/19/1998	03/27/2001	Economical Silicon-on-Silicon Hybrid Wafer Assembly
6248649	USA	06/17/1999	11/28/2000	Controlled Cleavage Process and Device for Patterned Films Using Patterned Implants
6269765	USA	10/01/1998	11/20/2001	Collection Devices for Plasma Immersion Ion Implantation
6274459	USA	02/16/1999	07/04/2000	Method for Non Mass Selected Ion Implant Profile Control
6284631	USA	01/10/2000	04/15/2003	Method and Device for Controlled Cleaving Process
6287941	USA	09/20/1999	05/10/2005	Surface Finishing of SOI Substrates Using an EPI Process
6290804	USA	02/19/1998	08/15/2000	Controlled Cleavage Process Using Patterning
6291313	USA	05/18/1999	08/07/2001	Method and Device for Controlled Cleaving Process
6291314	USA	06/17/1999	04/18/2000	Controlled Cleavage Process and Device for Patterned Films Using a Release Layer
6291326	USA	06/17/1999	04/17/2001	Pre-Semiconductor Process Implant and Post-Process Film Separation
6294814	USA	08/24/1999	09/19/2000	Cleaved Silicon Thin Film With Rough Surface
6300227	USA	12/01/1998	02/13/2001	Enhanced Plasma Mode, Method, and System for Plasma Immersion Ion Implantation
6321134	USA	07/28/1998	05/08/2001	Cluster Tool System Software Using Plasma Immersion Ion Implantation
6335264	USA	09/15/2000	06/06/2006	Controlled Cleavage Thin Film Separation Process Using a Reusable Substrate
6338313	USA	04/24/1998	05/27/2008	System for the Plasma Treatment of Large Area Substrates
6391740	USA	04/28/1999	10/24/2012	Generic Layer Transfer Methodology by Controlled Cleavage Process
6448152	USA	07/16/2001	04/29/2003	Method and System for Generating a Plurality of Donor Wafers and Handle Wafers Prior to an Order Being Placed by a Customer
6455399	USA	03/14/2001	05/21/2002	Smoothing Method for Cleaved Films Made Using Thermal Treatment
6458672	USA	11/02/2000	08/14/2001	Controlled Cleavage Process and Resulting Device Using Beta Annealing
6458723	USA	06/14/2000	02/04/2003	High Temperature Implant Method and Apparatus
6486041	USA	02/20/2001	04/24/2001	Method and Device for Controlled Cleaving Process
6489241	USA	09/17/1999	09/05/2000	Surfacing Finishing of SOI Substrates Using an EPI Process
6500732	USA	07/27/2000	09/18/2001	Cleaving Process to Fabricate Multilayered Substrates Using Low Implantation Doses
6511899	USA	05/06/1999	02/06/2001	Controlled Cleavage Process Using Pressurized Fluid
6513564	USA	03/14/2001	06/19/2001	Nozzle for Cleaving Substrates
6514838	USA	06/27/2001	09/18/2001	Method for Non Mass Selected Ion Implant Profile Control
6528391	USA	05/21/1999	10/09/2001	Controlled Cleavage Process and Device for Patterned Films
6534381	USA	01/04/2000	04/10/2001	Method for Fabricating Multi-Layered Substrates
6544862	USA	01/14/2000	03/18/2003	Particle Distribution Method and Resulting Structure for a Layer Transfer Process
6548382	USA	08/04/2000	01/09/2001	Gettering Technique for Wafers Made Using a Controlled Cleaving Process

SiGen Patent Portfolio

Patent Number	Country	Filed	Issued	Title
6554046	USA	11/27/2000	11/29/2005	Substrate Cleaving Tool and Method
6558802	USA	02/29/2000	09/05/2007	Silicon-On-Silicon Hybrid Wafer Assembly
6582999	USA	04/05/2001	09/05/2007	Controlled Cleavage Process Using Pressurized Fluid
6632324	USA	06/18/1997	09/05/2007	System for the Plasma Treatement of Large Area Substrates
6632724	USA	01/13/2000	09/11/2001	Controlled Cleaving Process
6645828	USA	09/08/2000	08/07/2007	In Situ Plasma Wafer Bonding Method
6780759	USA	10/01/2001	04/19/2005	Method for Multi-Frequency Bonding
6790747	USA	10/09/2002	03/20/2001	Method and Device for Controlled Cleaving Process
6881644	USA	05/17/2002	09/24/2002	Smoothing Method for Cleaved Films Made Using a Release Layer
6890838	USA	03/26/2003	02/04/2003	Gettering Technique for Wafers Made Using a Controlled Cleaving Process
6908832	USA	10/06/2003	10/01/2002	In Situ Plasma Wafer Bonding Method
6969668	USA	11/08/2000	12/31/2002	Treatment Method of Film Quality for the Manufacture of Substrates
7056808	USA	11/20/2002	04/08/2003	Cleaving Process to Fabricate Multilayered Substrates Using Low Implantation Doses
7078317	USA	08/06/2004	08/24/2004	Method and System for Source Switching and In-Situ Plasma Bonding
7094666	USA	01/24/2005	04/08/2008	Method and System for Fabricating Strained Layers for the Manufacture of Integrated Circuits
7147709	USA	11/14/2003	12/09/2008	Non-Contact Etch Annealing of Strained Layers
7160790	USA	8/19/2003	1/9/2007	Controlled Cleaving Process
7166520	USA	08/08/2005	06/24/2008	Thin Handle Substrate Method and Structure for Fabricating Devices Using One or More Films Provided by a Layer Transfer Process
7253081	USA	06/26/2001	07/18/2006	Surface Finishing of SOI Substrates Usina an EPI Process
7348258	USA	08/06/2004	08/22/2006	Method and Device for Controlled Cleaving Process
7351644	USA	09/14/2006	06/24/2008	Thin Handle Substrate Method and Structure for Fabricating Devices Using One or More Films Provided by a Layer Transfer Process
7354815	USA	11/17/2004	09/29/2009	Method for Fabricating Semiconductor Devices Using Strained Silicon Bearing Material
7371660	USA	11/16/2005	5/13/2008	Controlled Cleaving Process
7378330	USA	03/28/2006	12/30/2009	Cleaving Process to Fabricate Multilayered Substrates Using Low Implantation Doses
7390724	USA	04/11/2005	02/28/2008	Method and System for Lattice Space Engineering
7391047	USA	03/17/2006	5/29/2012	Method and System for Fabricating Strained Layers for the Manufacture of Integrated Circuits
7399680	USA	11/30/2005	05/10/2006	A Method and Structure for Implanting Bonded Substrates for Electrical Conductivity
7410887	USA	01/26/2007	12/12/2006	Controlled Process and Resulting Device
7427554	USA	08/12/2005	06/16/2009	Manufacturing Strained Silicon Substrates Using a Backing Material
7462526	USA	06/09/2005	04/21/2010	Method for Fabricating Semiconductor Devices Using Strained Silicon Bearing Material
7470600	USA	8/20/2007	12/30/2008	Method and Device for Controlled cleaving Process
7479441	USA	10/13/2006	12/08/2009	Method and Apparatus for Flag-Less Wafer Bonding Tool
7547609	USA	11/15/2005	08/24/2011	Method and Structure for Implanting Bonded Substrates for Electrical Conductivity
7595499	USA	02/19/2008	08/14/2012	Method and System for Fabricating Strained Layers for the Manufacture of Integrated Circuits
7598153	USA	03/31/2006	08/10/2010	Method and Structure for Fabricating Bonded Substrate Structures Using Thermal Processing to Remove Oxygen Species
7629666	USA	06/12/2008	03/09/2010	Method and Structure for Implanting Bonded Substrates for Electrical Conductivity
7674687	USA	07/27/2005	03/22/2011	Method and Structure for Fabricating Multiple Tiled Regions onto a Plate Using a Controlled Cleaving Process
7759217	USA	01/26/2007	09/06/2011	Controlled Process and Resulting Device
7759220	USA	04/05/2007	12/06/2011	Method and Structure for Fabricating Solar Cells Using a Layer Transfer Processes
7772088	USA	02/24/2006	09/23/2008	Applications and Equipment of Substrate Stiffness Method and Resulting Devices for Layer Transfer Processes on Quartz or Glass
7776717	USA	08/20/2007	01/23/2007	Controlled Process and Resulting Device
7781305	USA	03/31/2008	04/01/2008	Controlled Cleaving Process
7811900	USA	09/07/2007		Method and Structure for Fabricating Solar Cells Using a Thick Layer Transfer Process
7811901	USA	12/01/2008	01/04/2007	Method and Edge Region Structure Using Co-Implanted Particles for Layer Transfer Processes
7846818	USA	07/10/2008	09/06/2011	Controlled Process and Resulting Device
7863157	USA	03/13/2007	01/20/2009	Method and Structure for Fabricating Solar Cells Using A Layer Transfer Process
7910456	USA	05/25/2007	11/19/2010	Liquid Based Substrate Method and Structure for Layer Transfer Applications
7910458	USA	01/25/2008	10/06/2009	Method and Structure Using Selected Implant Angles Using a Linear Accelerator Process for Manufacture of Free Standing Films of Materials
7911016	USA	01/27/2010	07/20/2010	Method and Structure for Fabricating Multiple Tiled Regions onto a Plate Using a Controlled Cleaving Process
8012851	USA	03/24/2010	03/22/2011	Method and Structure for Fabricating Solar Cells Using A Layer Transfer Process
8012852	USA	05/27/2010	04/24/2013	Controlled Process and Resulting Device
8012855	USA	01/27/2010	04/10/2012	Method and Structure for Fabricating Multiple Tiled Regions onto a Plate Using a Controlled Cleaving Process
8071463	USA	01/27/2010	06/27/2012	Method and Structure for Fabricating Multiple Tiled Regions onto a Plate Using a Controlled Cleaving Process
8110480	USA	03/23/2010	10/12/2010	Method and Structure for Fabricating Solar Cells Using a Thick Layer Transfer Process
8124499	USA	11/05/2007	02/07/2012	Method and Structure for Thick Layer Transfer Using a Linear Accelerator
8133800	USA	07/23/2009	10/22/2013	Free-Standing Thickness of Single Crystal Material and Method Having Carrier Lifetimes
8143165	USA	02/09/2009		Method for Fabricating Semiconductor Devices Using Strained Silicon Bearing Material
8,153,513	USA	07/24/2007	02/28/2012	Method and System for Continuous Large-Area Scanning Implantation Process
8187377	USA	10/04/2002	05/04/2011	Non-Contact Etch Annealing of Strained Layers
8,222,119	USA	09/27/2011	03/22/2011	Apparatus and Method of Temperature Control During Cleaving Processes of Thick Film Materials
8241996	USA	02/24/2006		Substrate Stiffness Method and Resulting Devices for Layer Transfer Process
8293619	USA	07/24/2009	07/17/2012	Layer Transfer of Films Utilizing Controlled Propagation
8329557	USA	05/12/2010	10/12/2010	Techniques for Forming Thin Films by Implantation with Reduced Channeling
8330126	USA	07/29/2009	12/25/2013	Race Track Configuration and Method for Wafering Silicon Solar Substrates
8,563,402	USA	08/13/2011		Method and Structure for Fabricating Solar Cells Using a Thick Layer Transfer Process
8,623,137	USA	04/10/2009	1/7/2014	Method and Device for Slicing a Shaped Silicon Ingot Using Layer Transfer

SiGen Patent Portfolio

Patent Number	Country	Filed	Issued	Title
8637382	USA	08/01/2011	05/31/2012	Layer Transfer of Films Utilizing Thermal Flux Regime For Energy Controlled Cleaving.
	Japan	03/16/2007	03/13/2012	Method and Structure for Fabricating Solar Cells
	EPO	05/07/2009	1/28/2014	Layer Transfer of Films Utilizing Controlled Shear Region
10-0810825	Korea (South)	01/10/2005	06/29/2012	An Apparatus and Method for Controlled Cleaving
10-0996539	Korea (South)	01/19/2007	12/11/2012	Method and Structure for Fabricating Bonded Substrate Structures Using Thermal Processing to Remove Oxygen Species
10-1154133	Korea (South)	08/31/2009	10/23/2012	Free-Standing Thickness of Single Crystal Material and Method Having Carrier Lifetimes
10-1163282	Korea (South)	08/25/2009	12/11/2012	Race Track Configuration and Method for Wafering Silicon Solar Substrates
ZL 200780022933.9	China	09/10/2007	12/03/2002	Method and Structure for Fabricating Solar Cells Using a Thick Layer Transfer Process
ZL 200810006997.6	China	01/28/2008	01/30/2001	Apparatus and Method of Temperature Control During Cleaving Processes of Thick Film Materials
ZL 200910138229.0	China	05/07/2009	11/11/2003	Layer Transfer of Films Utilizing Controlled Shear Region
ZL200580002085.6	China	01/10/2005	06/21/2005	An Apparatus and Method for Controlled Cleaving
ZL2006101629001.1	China	11/29/2006	11/27/2002	A Method and Structure for Implanting Bonded Substrates for Electrical Conductivity
ZL200680014752.7	China	02/24/2006	05/23/2008	Substrate Stiffness Method and Resulting Devices
ZL200780026734.5	China	07/25/2007	08/05/1997	Continuous Large-Area Scanning Implantation Process
ZL200780041135.0	China	11/06/2007	10/14/2003	Method and Structure for Thick Layer Transfer Using A Linear Accelerator
ZL200810009149.0	China	01/29/2008	01/15/2002	Method for Fabricating Free Standing Thickness of Materials Using One or More Semiconductor Substrates
ZL98804976.7	China	05/11/1998	08/31/1999	A Controlled Cleavage Process

B6D (Official Form 6D) (12/07)

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

SCHEDULE D - CREDITORS HOLDING SECURED CLAIMS

State the name, mailing address, including zip code, and last four digits of any account number of all entities holding claims secured by property of the debtor as of the date of filing of the petition. The complete account number of any account the debtor has with the creditor is useful to the trustee and the creditor and may be provided if the debtor chooses to do so. List creditors holding all types of secured interests such as judgment liens, garnishments, statutory liens, mortgages, deeds of trust, and other security interests.

List creditors in alphabetical order to the extent practicable. If a minor child is a creditor, the child's initials and the name and address of the child's parent or guardian, such as "A.B., a minor child, by John Doe, guardian." Do not disclose the child's name. See, 11 U.S.C. §112 and Fed. R. Bankr. P. 1007(m). If all secured creditors will not fit on this page, use the continuation sheet provided.

If any entity other than a spouse in a joint case may be jointly liable on a claim, place an "X" in the column labeled "Codebtor" ,include the entity on the appropriate schedule of creditors, and complete Schedule H - Codebtors. If a joint petition is filed, state whether the husband, wife, both of them, or the marital community may be liable on each claim by placing an "H", "W", "J", or "C" in the column labeled "Husband, Wife, Joint, or Community".

If the claim is contingent, place an "X" in the column labeled "Contingent". If the claim is unliquidated, place an "X" in the column labeled "Unliquidated". If the claim is disputed, place an "X" in the column labeled "Disputed". (You may need to place an "X" in more than one of these three columns.)

Total the columns labeled "Amount of Claim Without Deducting Value of Collateral" and "Unsecured Portion, if Any" in the boxes labeled "Total(s)" on the last sheet of the completed schedule. Report the total from the column labeled "Amount of Claim" also on the Summary of Schedules and, if the debtor is an individual with primarily consumer debts, report the total from the column labeled "Unsecured Portion" on the Statistical Summary of Certain Liabilities and Related Data.

☐ Check this box if debtor has no creditors holding secured claims to report on this Schedule D.

CREDITOR'S NAME AND MAILING ADDRESS INCLUDING ZIP CODE, AND ACCOUNT NUMBER (See instructions above.)	CODEBTOR	Husband, Wife, Joint, or Community H W J C	DATE CLAIM WAS INCURRED, NATURE OF LIEN, AND DESCRIPTION AND VALUE OF PROPERTY SUBJECT TO LIEN	CONTINGENT	UNLIQUIDATED	DISPUTED	AMOUNT OF CLAIM WITHOUT DEDUCTING VALUE OF COLLATERAL	UNSECURED PORTION, IF ANY
Account No. **Firsthand Capital Management, Inc, Agent** **150 Almaden Blvd., Ste. 95113** **San Jose, CA 95113**		**-**	**for notice purposes** Value $ **0.00**			**X**	**0.00**	**0.00**
Account No. **Firsthand Technology Value Fund, Inc.** **150 Almaden Blvd.** **Suite #1250** **San Jose, CA 95113**		**-**	**11/03/2010** **Non-Purchase Money Security** **accounts receivable and payment intangibles, equipment, intellectual property** Value $ **16,411,872.00**			**X**	**7,688,182.09**	**0.00**
Account No.			Value $					
Account No.			Value $					

0 continuation sheets attached

Subtotal (Total of this page)	**7,688,182.09**	**0.00**
Total (Report on Summary of Schedules)	**7,688,182.09**	**0.00**

In re **Silicon Genesis Corporation**,
Debtor

Case No. **15-50525 MEH**

SCHEDULE E - CREDITORS HOLDING UNSECURED PRIORITY CLAIMS

A complete list of claims entitled to priority, listed separately by type of priority, is to be set forth on the sheets provided. Only holders of unsecured claims entitled to priority should be listed in this schedule. In the boxes provided on the attached sheets, state the name, mailing address, including zip code, and last four digits of the account number, if any, of all entities holding priority claims against the debtor or the property of the debtor, as of the date of the filing of the petition. Use a separate continuation sheet for each type of priority and label each with the type of priority.

The complete account number of any account the debtor has with the creditor is useful to the trustee and the creditor and may be provided if the debtor chooses to do so. If a minor child is a creditor, state the child's initials and the name and address of the child's parent or guardian, such as "A.B., a minor child, by John Doe, guardian." Do not disclose the child's name. See, 11 U.S.C. §112 and Fed. R. Bankr. P. 1007(m).

If any entity other than a spouse in a joint case may be jointly liable on a claim, place an "X" in the column labeled "Codebtor," include the entity on the appropriate schedule of creditors, and complete Schedule H-Codebtors. If a joint petition is filed, state whether the husband, wife, both of them, or the marital community may be liable on each claim by placing an "H," "W," "J," or "C" in the column labeled "Husband, Wife, Joint, or Community." If the claim is contingent, place an "X" in the column labeled "Contingent." If the claim is unliquidated, place an "X" in the column labeled "Unliquidated." If the claim is disputed, place an "X" in the column labeled "Disputed." (You may need to place an "X" in more than one of these three columns.)

Report the total of claims listed on each sheet in the box labeled "Subtotals" on each sheet. Report the total of all claims listed on this Schedule E in the box labeled "Total" on the last sheet of the completed schedule. Report this total also on the Summary of Schedules.

Report the total of amounts entitled to priority listed on each sheet in the box labeled "Subtotals" on each sheet. Report the total of all amounts entitled to priority listed on this Schedule E in the box labeled "Totals" on the last sheet of the completed schedule. Individual debtors with primarily consumer debts report this total also on the Statistical Summary of Certain Liabilities and Related Data.

Report the total of amounts not entitled to priority listed on each sheet in the box labeled "Subtotals" on each sheet. Report the total of all amounts not entitled to priority listed on this Schedule E in the box labeled "Totals" on the last sheet of the completed schedule. Individual debtors with primarily consumer debts report this total also on the Statistical Summary of Certain Liabilities and Related Data.

☐ Check this box if debtor has no creditors holding unsecured priority claims to report on this Schedule E.

TYPES OF PRIORITY CLAIMS (Check the appropriate box(es) below if claims in that category are listed on the attached sheets)

☐ **Domestic support obligations**

Claims for domestic support that are owed to or recoverable by a spouse, former spouse, or child of the debtor, or the parent, legal guardian, or responsible relative of such a child, or a governmental unit to whom such a domestic support claim has been assigned to the extent provided in 11 U.S.C. § 507(a)(1).

☐ **Extensions of credit in an involuntary case**

Claims arising in the ordinary course of the debtor's business or financial affairs after the commencement of the case but before the earlier of the appointment of a trustee or the order for relief. 11 U.S.C. § 507(a)(3).

☐ **Wages, salaries, and commissions**

Wages, salaries, and commissions, including vacation, severance, and sick leave pay owing to employees and commissions owing to qualifying independent sales representatives up to $12,475* per person earned within 180 days immediately preceding the filing of the original petition, or the cessation of business, whichever occurred first, to the extent provided in 11 U.S.C. § 507(a)(4).

☐ **Contributions to employee benefit plans**

Money owed to employee benefit plans for services rendered within 180 days immediately preceding the filing of the original petition, or the cessation of business, whichever occurred first, to the extent provided in 11 U.S.C. § 507(a)(5).

☐ **Certain farmers and fishermen**

Claims of certain farmers and fishermen, up to $6,150* per farmer or fisherman, against the debtor, as provided in 11 U.S.C. § 507(a)(6).

☐ **Deposits by individuals**

Claims of individuals up to $2,775* for deposits for the purchase, lease, or rental of property or services for personal, family, or household use, that were not delivered or provided. 11 U.S.C. § 507(a)(7).

☒ **Taxes and certain other debts owed to governmental units**

Taxes, customs duties, and penalties owing to federal, state, and local governmental units as set forth in 11 U.S.C. § 507(a)(8).

☐ **Commitments to maintain the capital of an insured depository institution**

Claims based on commitments to the FDIC, RTC, Director of the Office of Thrift Supervision, Comptroller of the Currency, or Board of Governors of the Federal Reserve System, or their predecessors or successors, to maintain the capital of an insured depository institution. 11 U.S.C. § 507 (a)(9).

☐ **Claims for death or personal injury while debtor was intoxicated**

Claims for death or personal injury resulting from the operation of a motor vehicle or vessel while the debtor was intoxicated from using alcohol, a drug, or another substance. 11 U.S.C. § 507(a)(10).

* *Amount subject to adjustment on 4/01/16, and every three years thereafter with respect to cases commenced on or after the date of adjustment.*

1 continuation sheets attached

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

SCHEDULE E - CREDITORS HOLDING UNSECURED PRIORITY CLAIMS

(Continuation Sheet)

Taxes and Certain Other Debts Owed to Governmental Units

TYPE OF PRIORITY

CREDITOR'S NAME, AND MAILING ADDRESS INCLUDING ZIP CODE, AND ACCOUNT NUMBER (See instructions.)	CODEBTOR	Husband, Wife, Joint, or Community H W J C	DATE CLAIM WAS INCURRED AND CONSIDERATION FOR CLAIM	CONTINGENT	UNLIQUIDATED	DISPUTED	AMOUNT OF CLAIM	AMOUNT NOT ENTITLED TO PRIORITY, IF ANY	AMOUNT ENTITLED TO PRIORITY
Account No. **97-329546** **California State Board of Equalization** **PO Box 942879** **Sacramento, CA 94279-0001**		-					**186.00**	**0.00**	**186.00**
Account No. **Tax Collector, Santa Clara County** **70 West Hedding St.** **East Wing, 6th Flr** **San Jose, CA 95110-1767**		-					**Unknown**	**Unknown**	**Unknown**
Account No.									
Account No.									
Account No.									

Sheet **1** of **1** continuation sheets attached to Schedule of Creditors Holding Unsecured Priority Claims

	AMOUNT OF CLAIM	AMOUNT NOT ENTITLED TO PRIORITY, IF ANY	AMOUNT ENTITLED TO PRIORITY
Subtotal (Total of this page)	**186.00**	**0.00**	**186.00**
Total (Report on Summary of Schedules)	**186.00**	**0.00**	**186.00**

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

SCHEDULE F - CREDITORS HOLDING UNSECURED NONPRIORITY CLAIMS

State the name, mailing address, including zip code, and last four digits of any account number, of all entities holding unsecured claims without priority against the debtor or the property of the debtor, as of the date of filing of the petition. The complete account number of any account the debtor has with the creditor is useful to the trustee and the creditor and may be provided if the debtor chooses to do so. If a minor child is a creditor, state the child's initials and the name and address of the child's parent or guardian, such as "A.B., a minor child, by John Doe, guardian." Do not disclose the child's name. See, 11 U.S.C. §112 and Fed. R. Bankr. P. 1007(m). Do not include claims listed in Schedules D and E. If all creditors will not fit on this page, use the continuation sheet provided.

If any entity other than a spouse in a joint case may be jointly liable on a claim, place an "X" in the column labeled "Codebtor," include the entity on the appropriate schedule of creditors, and complete Schedule H - Codebtors. If a joint petition is filed, state whether the husband, wife, both of them, or the marital community may be liable on each claim by placing an "H," "W," "J," or "C" in the column labeled "Husband, Wife, Joint, or Community."

If the claim is contingent, place an "X" in the column labeled "Contingent." If the claim is unliquidated, place an "X" in the column labeled "Unliquidated." If the claim is disputed, place an "X" in the column labeled "Disputed." (You may need to place an "X" in more than one of these three columns.)

Report the total of all claims listed on this schedule in the box labeled "Total" on the last sheet of the completed schedule. Report this total also on the Summary of Schedules and, if the debtor is an individual with primarily consumer debts, report this total also on the Statistical Summary of Certain Liabilities and Related Data.

☐ Check this box if debtor has no creditors holding unsecured claims to report on this Schedule F.

CREDITOR'S NAME, MAILING ADDRESS INCLUDING ZIP CODE, AND ACCOUNT NUMBER (See instructions above.)	CODEBTOR	Husband, Wife, Joint, or Community H W J C	DATE CLAIM WAS INCURRED AND CONSIDERATION FOR CLAIM. IF CLAIM IS SUBJECT TO SETOFF, SO STATE.	CONTINGENT	UNLIQUIDATED	DISPUTED	AMOUNT OF CLAIM
Account No. **1800flowers (VISA)**		-					**0.00**
Account No. **ACIP International, Inc (PATENT)** **1280 Boulevard Way, Suite# 202** **Walnut Creek, CA 94595**		-					**956.20**
Account No. **Air Products & Chemicals, Inc.** **P.O Box# 935430** **Atlanta, GA 31193-5430**		-					**2,210.89**
Account No. **Airgas USA, LLC.** **P.O Box# 7423** **Pasadena, CA 91109-7423**		-					**93.54**

5 continuation sheets attached

Subtotal (Total of this page) **3,260.63**

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

SCHEDULE F - CREDITORS HOLDING UNSECURED NONPRIORITY CLAIMS

(Continuation Sheet)

CREDITOR'S NAME, MAILING ADDRESS INCLUDING ZIP CODE, AND ACCOUNT NUMBER (See instructions above.)	CODEBTOR	Husband, Wife, Joint, or Community H W J C	DATE CLAIM WAS INCURRED AND CONSIDERATION FOR CLAIM. IF CLAIM IS SUBJECT TO SETOFF, SO STATE.	CONTINGENT	UNLIQUIDATED	DISPUTED	AMOUNT OF CLAIM
Account No. **Alston & Bird, LLP (Law Firm)** **P.O Box# 933124** **Atlanta, GA 31193-3124**		-					**35,807.23**
Account No. **AT&T - fka SBC/Pacific Bell** **P.O. Box# 5025** **Carol Stream, IL 60197-5025**		-					**69.01**
Account No. **AT&T Ethernet** **P.O. Box# 5019** **Carol Stream, IL 60197-5019**		-					**4,034.12**
Account No. **Beijing East IP Ltd. (PATENT)** **Tower E2, The Towers** **Oriental Plaza No. East Chang An Ave.** **Suite# 1601, Dongchen District** **Beijing, P. 100738**		-					**1,575.59**
Account No. **Datasafe, Inc** **P.O. Box 7794** **San Francisco, CA 94120**		-					**1,183.13**

Sheet no. **1** of **5** sheets attached to Schedule of Creditors Holding Unsecured Nonpriority Claims

Subtotal (Total of this page) **42,669.08**

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

SCHEDULE F - CREDITORS HOLDING UNSECURED NONPRIORITY CLAIMS

(Continuation Sheet)

CREDITOR'S NAME, MAILING ADDRESS INCLUDING ZIP CODE, AND ACCOUNT NUMBER (See instructions above.)	CODEBTOR	Husband, Wife, Joint, or Community H W J C	DATE CLAIM WAS INCURRED AND CONSIDERATION FOR CLAIM. IF CLAIM IS SUBJECT TO SETOFF, SO STATE.	CONTINGENT	UNLIQUIDATED	DISPUTED	AMOUNT OF CLAIM
Account No. **Federal Express** **P.O. Box 7221** **Pasadena, CA 91109-7321**		**-**					**161.75**
Account No. **GE Mobile Water, Inc.** **P.O. Box# 742132** **Los Angeles, CA 90074-2132**		**-**					**169.66**
Account No. **Home Depot, The** **Home Depot Credit Services Dept.** **32-2501** **P.O. Box# 9055** **Des Moines, IA 50368-9055**		**-**					**556.19**
Account No. **J.D. Molex One, LLC** **1484 Saratoga Ave.** **Saratoga, CA 95070**		**-**	**11/18/2014** **restoration of former business premises**		**X**		**180,000.00**
Account No. **JB Precision, Inc.** **1640 Dell Ave.** **Campbell, CA 95008**		**-**					**1,763.54**

Sheet no. **2** of **5** sheets attached to Schedule of Creditors Holding Unsecured Nonpriority Claims

Subtotal (Total of this page) **182,651.14**

In re **Silicon Genesis Corporation**, Debtor Case No. **15-50525 MEH**

SCHEDULE F - CREDITORS HOLDING UNSECURED NONPRIORITY CLAIMS

(Continuation Sheet)

CREDITOR'S NAME, MAILING ADDRESS INCLUDING ZIP CODE, AND ACCOUNT NUMBER (See instructions above.)	CODEBTOR	Husband, Wife, Joint, or Community H W J C	DATE CLAIM WAS INCURRED AND CONSIDERATION FOR CLAIM. IF CLAIM IS SUBJECT TO SETOFF, SO STATE.	CONTINGENT	UNLIQUIDATED	DISPUTED	AMOUNT OF CLAIM
Account No. **Landauer, Inc.** **P.O Box 809051** **Chicago, IL 60680-9051**		-					**326.90**
Account No. **Mathys & Squire LLP (PATENT)** **32 London Bridge Street** **London SE1 9SG, Un**		-					**2,285.71**
Account No. **Oh, Back & Hahm (Patents- Korea)** **996-14 Deachidong** **Kangnamgu 4th. Fl. HANA Bldg.** **Seoul, Re 135-502**		-					**1,546.31**
Account No. **PG&E** **P.O. Box 997300** **Sacramento, CA 95899-7300**		-					**1,087.53**
Account No. **Pitney Bowes Global Financial Svcs, LLC** **PO Box# 371887** **Pittsburgh, PA 15250-7887**		-					**32.00**

Sheet no. **3** of **5** sheets attached to Schedule of Creditors Holding Unsecured Nonpriority Claims

Subtotal (Total of this page) **5,278.45**

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

SCHEDULE F - CREDITORS HOLDING UNSECURED NONPRIORITY CLAIMS

(Continuation Sheet)

CREDITOR'S NAME, MAILING ADDRESS INCLUDING ZIP CODE, AND ACCOUNT NUMBER (See instructions above.)	CODEBTOR	Husband, Wife, Joint, or Community H W J C	DATE CLAIM WAS INCURRED AND CONSIDERATION FOR CLAIM. IF CLAIM IS SUBJECT TO SETOFF, SO STATE.	CONTINGENT	UNLIQUIDATED	DISPUTED	AMOUNT OF CLAIM
Account No. **Pitney Bowes Postage by Phone** **P.O Box# 371874** **Pittsburgh, PA 15250-7874**		-					**50.00**
Account No. **Republic Services, Inc.** **Republic Svcs of Santa Clara County** **P.O Box# 78829** **Phoenix, AZ 85062-8829**		-					**3,451.14**
Account No. **Shred Works, Inc.** **Dept# 34654** **P.O Box# 3900** **San Francisco, CA 94139**		-					**261.00**
Account No. **Stearn Research Center** **Owner's Association** **7917 Winged Foot Court** **Pleasanton, CA 94588**		-					**4,182.62**
Account No. **U.S. Bank / Visa Business Account** **PO Box 790408** **St. Louis, MO 63179-0408**		-					**142.76**

Sheet no. **4** of **5** sheets attached to Schedule of Creditors Holding Unsecured Nonpriority Claims

Subtotal (Total of this page) **8,087.52**

In re **Silicon Genesis Corporation**, Case No. **15-50525 MEH**
Debtor

SCHEDULE F - CREDITORS HOLDING UNSECURED NONPRIORITY CLAIMS

(Continuation Sheet)

CREDITOR'S NAME, MAILING ADDRESS INCLUDING ZIP CODE, AND ACCOUNT NUMBER (See instructions above.)	CODEBTOR	Husband, Wife, Joint, or Community H W J C	DATE CLAIM WAS INCURRED AND CONSIDERATION FOR CLAIM. IF CLAIM IS SUBJECT TO SETOFF, SO STATE.	CONTINGENT	UNLIQUIDATED	DISPUTED	AMOUNT OF CLAIM
Account No. **W2 Systems** **106 Cresta Vista Drive** **San Francisco, CA 94127**		-					**8,557.94**
Account No. **Wilson Gunn** **Central Court 25 Southampton Bld.** **London, England WC2A 1AL**		-					**877.73**
Account No. **001000000029015** **XO Communications** **File 50550** **Los Angeles, CA 90074-0550**		-					**20.25**
Account No. **Yamakawa International Patent Office** **Shuwa-Tameike Bldg # 4-2** **Nagatacho 2, Chiyodaku, Tokyo,** **JAPAN**		-					**11,272.36**
Account No.							

Sheet no. **5** of **5** sheets attached to Schedule of Creditors Holding Unsecured Nonpriority Claims Subtotal (Total of this page)	**20,728.28**
Total (Report on Summary of Schedules)	**262,675.10**

B6G (Official Form 6G) (12/07)

In re **Silicon Genesis Corporation**, Debtor

Case No. **15-50525 MEH**

SCHEDULE G - EXECUTORY CONTRACTS AND UNEXPIRED LEASES

Describe all executory contracts of any nature and all unexpired leases of real or personal property. Include any timeshare interests. State nature of debtor's interest in contract, i.e., "Purchaser", "Agent", etc. State whether debtor is the lessor or lessee of a lease. Provide the names and complete mailing addresses of all other parties to each lease or contract described. If a minor child is a party to one of the leases or contracts, state the child's initials and the name and address of the child's parent or guardian, such as "A.B., a minor child, by John Doe, guardian." Do not disclose the child's name. See, 11 U.S.C. §112 and Fed. R. Bankr. P. 1007(m).

☐ Check this box if debtor has no executory contracts or unexpired leases.

Name and Mailing Address, Including Zip Code, of Other Parties to Lease or Contract	Description of Contract or Lease and Nature of Debtor's Interest. State whether lease is for nonresidential real property. State contract number of any government contract.
Alexander Meyer, Senior Director, New Business Development Applied Materials, Inc. 3050 Bowers Avenue, M/S 1954 Santa Clara, CA 95054	**[05/29/2003] Outbound lease of intellectual property**
Applied Materials, Inc. 3050 Bowers Avenue Attn: Jim Pursiano Santa Clara, CA 95054	**[04/30/1999] Outbound lease of intellectual property**
Applied Materials, Inc. 2881 Scott Blvd., M/S 2064 Attn: Joseph Sweeney, VP, Legal Affairs & Intellectual Property Santa Clara, CA 95054	**[05-29-2003] Outbound lease of intellectual property**
EV Group E. Thallner GmbH DI Erich Thallner Strasse 1 Attn: Dr. Peter Podesser A-4782 St. Florian am Inn, Austria	**[10/28/2003] Outbound lease of intellectual property**
QMAT, Inc. Attn: Francois Henley, President & CEO 2424 Walsh Avenue Santa Clara, CA 95051-1303	**[12/13/2012] Outbound lease of intellectual property 1/1/2015 - at will cost share agreement pursuant to which SiGen sharer R&D and admin space at 2424 Walsh Ave., Santa Clara, CA 95051**
Shin-Etsu Chemical Co., Ltd. 6-1, Ohtemachi 2-chome Chiyoda-ku, Tokyo 100-0004	**[06/09/2005] Outbound lease of intellectual property**
SunEdison, Inc. f/k/a MEMC Electronic Materials, Inc. 501 Pearl Drive Saint Peters, MO 63376	**[0701/2014] Outbound lease of intellectual property**

0 continuation sheets attached to Schedule of Executory Contracts and Unexpired Leases

In re **Silicon Genesis Corporation**, Case No. **15-50525 MEH**
Debtor

SCHEDULE H - CODEBTORS

Provide the information requested concerning any person or entity, other than a spouse in a joint case, that is also liable on any debts listed by debtor in the schedules of creditors. Include all guarantors and co-signers. If the debtor resides or resided in a community property state, commonwealth, or territory (including Alaska, Arizona, California, Idaho, Louisiana, Nevada, New Mexico, Puerto Rico, Texas, Washington, or Wisconsin) within the eight year period immediately preceding the commencement of the case, identify the name of the debtor's spouse and of any former spouse who resides or resided with the debtor in the community property state, commonwealth, or territory. Include all names used by the nondebtor spouse during the eight years immediately preceding the commencement of this case. If a minor child is a codebtor or a creditor, state the child's initials and the name and address of the child's parent or guardian, such as "A.B., a minor child, by John Doe, guardian." Do not disclose the child's name. See, 11 U.S.C. §112 and Fed. R. Bankr. P. 1007(m).

☒ Check this box if debtor has no codebtors.

NAME AND ADDRESS OF CODEBTOR	NAME AND ADDRESS OF CREDITOR

0 continuation sheets attached to Schedule of Codebtors

B6 Declaration (Official Form 6 - Declaration). (12/07)

United States Bankruptcy Court
Northern District of California

In re **Silicon Genesis Corporation** Case No. **15-50525 MEH**
Debtor(s) Chapter **11**

DECLARATION CONCERNING DEBTOR'S SCHEDULES

DECLARATION UNDER PENALTY OF PERJURY ON BEHALF OF CORPORATION OR PARTNERSHIP

I, the President and CEO of the corporation named as debtor in this case, declare under penalty of perjury that I have read the foregoing summary and schedules, consisting of **24** sheets, and that they are true and correct to the best of my knowledge, information, and belief.

Date **February 18, 2015** Signature **/s/ Theodore E. Fong**
Theodore E. Fong
President and CEO

Penalty for making a false statement or concealing property: Fine of up to $500,000 or imprisonment for up to 5 years or both. 18 U.S.C. §§ 152 and 3571.